PRELIMINARY PRODUCT INFORMATION



BIPOLAR ANALOG INTEGRATED CIRCUIT $\mu PC8232T5N$

SiGe: C LOW NOISE AMPLIFIER FOR GPS

DESCRIPTION

The μ PC8232T5N is a silicon germanium carbon (SiGe:C) monolithic integrated circuit designed as low noise amplifier for GPS. This device exhibits low noise figure and high power gain characteristics, so this IC can improve the sensitivity of GPS receiver. In addition, the μ PC8232T5N which is included output matching circuit contributes to reduce external components and system size.

The package is 6-pin plastic TSON (<u>Thin Small Out-line Non-leaded</u>) suitable for surface mount. This IC is manufactured using our UHS4 (Ultra High Speed Process) SiGe:C bipolar process.

FEATURES

Low noise : NF = 0.95 dB TYP. @ fin = 1575 MHz
 High gain : GP = 17 dB TYP. @ fin = 1575 MHz
 Low current consumption : Icc = 3.0 mA TYP. @ Vcc = 3.0V

• Built-in power-save function

• High-density surface mounting : 6-pin plastic TSON package (1.5 \times 1.5 \times 0.37 mm)

· Included output matching circuit

Included very robust bandgap regulator (Small Vcc and TA dependence)

· Included protection circuits for ESD

APPLICATION

· Low noise amplifier for GPS

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	S upplying Form
μP C 8232T 5N-E 2	μPC8232T5N-E2-A	6-pin plastic TSON (Pb-Free)	6L	 8mm wide embossed taping Pin 1, 6 face the perforation side of the tape Qty 3 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office.

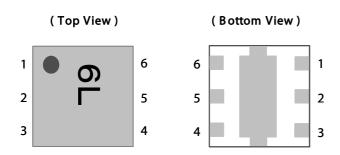
Part number for sample order: μ PC8232T5N

Caution Observe precautions when handling because these devices are sensitive electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

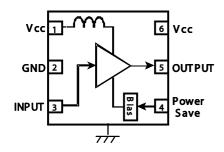
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PIN CONNECTIONS



P in No.	P in Name		
1	Vcc		
2	GND		
3	INPUT		
4	Power Save		
5	OUTPUT		
6	Vcc		
EXPOSED PAD	GND		

INTERNAL BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Parameter	S ymbol	Test Conditions	R atings	Unit
S upply Voltage	Vcc	T _A = + 25°C	4.0	V
Power-S aving Voltage	VPS	T _A = + 25°C	4.0	V
Total Power Dissipation	P tot	T _A = + 85°C Note	150	mW
Operating Ambient Temperature	Та		- 40 to + 85	°C
S torage Temperature	Tstg		- 55 to + 150	°C
Input Power	Pin		+ 10	dBm

Note Mounted on double-sided copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB

RECOMMENDED OPERATING RANGE

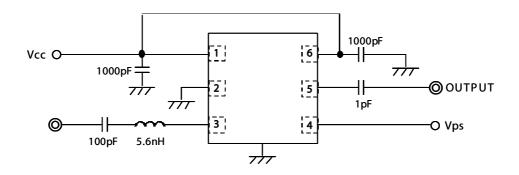
Parameter	S ymbol	MIN.	TYP.	MAX.	Unit
S upply Voltage	Vcc	2.5	3.0	3.3	V
Operating Ambient Temperature	TA	- 40	+ 25	+ 85	°C
Power Save Turn-on Voltage	VPSon	1.6	_	Vcc	V
Power Save Turn-off Voltage	V P S off	0	_	0.4	V

ELECTRICAL CHARACTERISTICS

 $(T_A = +25$ °C, $V_{CC} = V_{PS} = 3.0 \text{ V}$, $f_{in} = 1575 \text{MHz}$, unless otherwise specified)

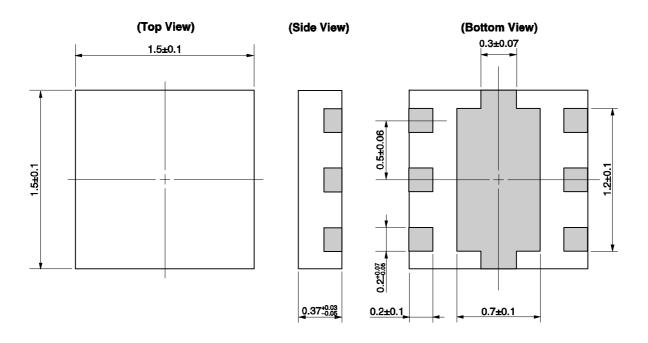
Parameter	S ymbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	lcc	No signal (V _{PS} = 3.0 V)	2.3	3.0	4.1	mA
		At Power-Saving Mode (VPS = 0 V)	-	_	1	μΑ
Power Gain	GР	Pin=-35dBm	15	17	19	dB
Noise Figure	NF		-	0.95	1.25	dB
Input R eturn Loss	R Lin		7	10	_	dB
Output Return Loss	R Lout		10	20	_	dB
Isolation	IS L		I	40	_	dB
Input 3rd Order Distortion I Intercept Point	IIP ₃	fin1=1574MHz, fin2=1575MHz	1	- 8	_	dB m
Gain 1 dB Compression Intput Power	P in (1 dB)		_	-21	_	dBm

TEST CIRCUITS



PACKAGE DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)



NOTE ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation). All the ground pins must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to Vcc line.
- (4) Do not supply DC voltage to INPUT pin.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

S oldering Method	S oldering C onditions		Condition Symbol
Infrared Reflow	P eak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher P reheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of ros in flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR 260
W ave S oldering	P eak temperature (molten solder temperature) Time at peak temperature P reheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of ros in flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	W S 260
Partial Heating	P eak temperature (pin temperature) S oldering time (per side of device) Maximum chlorine content of ros in flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS 350

Caution Do not use different soldering methods together (except for partial heating).



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Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
PBB	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

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